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Li et al.(10) **Pub. No.: US 2023/0232543 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **DIE PACKAGE STRUCTURE AND METHOD
FOR FABRICATING THE SAME**(71) Applicant: **REALTEK SEMICONDUCTOR
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(2013.01)(57) **ABSTRACT**

A die package structure and a method for fabricating the same are provided. The method includes: fixing a first die on a package base; aligning first hollow pads of a flexible printed circuit board with first pads of the first die, and fixing the flexible printed circuit board; soldering the first hollow pads to the first pads; fixing a second die on the flexible printed circuit board to overlap with the first die; folding the flexible printed circuit board, such that second hollow pads of the flexible printed circuit board are aligned with second pads of the second die, and signal test pads of the flexible printed circuit board are exposed; fixing the flexible printed circuit board on the second die; soldering the second hollow pads to the second pads; soldering metal wires to the signal test soldering pads; and soldering package pins to the metal wires.

